

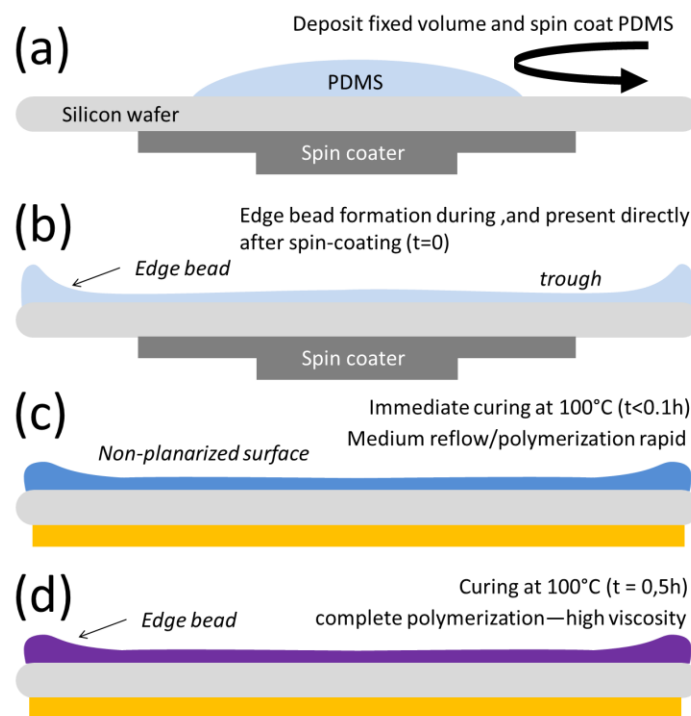
Supplementary Information for:

Planarization and edge bead reduction of spin-coated polydimethylsiloxane

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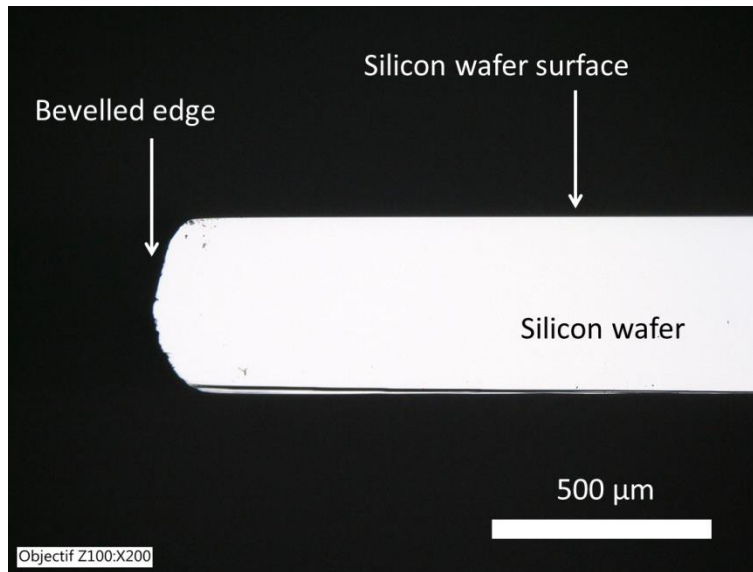
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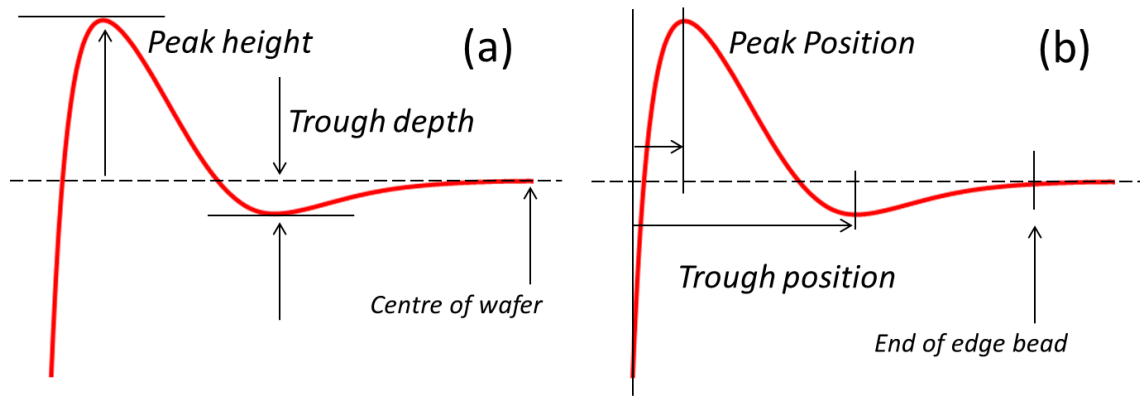


Supplementary Information Figure S1. Schematic diagram illustrating the classic 'often-used' fabrication steps used which result in non-planarized PDMS thick films containing edge beads. (a) A fixed volume (~8 ml) of PDMS is deposited onto the centre of the silicon wafer followed by spin coating. (b) The sample

immediately after spin-coating is finished. (c) The sample is cured on a levelled hot-plate (100°C) immediately after spin coating. (d) Polymerization of the PDMS is complete leaving non-negligible edge beads and a non-uniform thickness.



Supplementary Information Figure S2. A photograph showing the shape of the bevelled edge of the commercial silicon wafer.



Supplementary Information Figure S3. A guide to the edge bead dimensions measured that are presented in Figures 4 and 7 of the manuscript. (a) Edge bead peak height and trough depth. (b) Edge bead peak position and trough position.